



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-26
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC30H12CWL	88PN*01HC1T7	A	Z45A	2018-01-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	6100	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.77 - 20.83 - 4.9	3	Through-hole	
Comment	Package: TO247 LONG LEADS			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.13	Die	21

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	88PN*01HC1T7					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	11.297	mg	supplier	die	Silicium carbide	409-21-2		10.860	mg	961317	1780
				supplier	metallization	Aluminium (Al)	7429-90-5		0.087	mg	7701	14
				supplier	metallization	Gold (Au)	7440-57-5		0.013	mg	1151	2
				supplier	passivation	Nickel (Ni)	7440-02-0		0.069	mg	6108	11
				supplier	metallization	Silver (Ag)	7440-22-4		0.148	mg	13101	24
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	442	1
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	354	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.013	mg	1151	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.060	mg	5311	10
				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.038	mg	3364	6
Leadframe	Copper & its alloys	3553.151	mg	supplier	alloy	Copper (Cu)	7440-50-8		3546.401	mg	998100	581377
				supplier	alloy	Iron (Fe)	7439-89-6		5.330	mg	1500	874
				supplier	alloy	Phosphorus (P)	12185-10-3		1.420	mg	400	233
Soft solder	Other Organic Materials	49.023	mg	supplier	solder	Tin (Sn)	7440-31-5		31.864	mg	649981	5224
				supplier	solder	Silver (Ag)	7440-22-4		12.256	mg	250005	2009
				supplier	solder	Antimony (Sb)	7440-36-0		4.903	mg	100014	804
Bonding wire	Other inorganic materials	39.306	mg	supplier	wire	Aluminium (Al)	7429-90-5		39.306	mg	1000000	6444
Encapsulation	Other Organic materials	2419.751	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1894.665	mg	783000	310601
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		362.962	mg	150000	59502
				supplier	mold compound	Phenol resin	9003-35-4		120.987	mg	50000	19834
				supplier	mold compound	Triphenylphosphine	603-35-0		19.357	mg	8000	3173
				supplier	mold compound	Bismuth compound	Proprietary		12.099	mg	5000	1983
Connections coating	Solder	27.472	mg	supplier	mold compound	Carbon Black	1333-86-4		9.681	mg	4000	1587
				supplier	solder alloy	Tin (Sn)	7440-31-5		27.472	mg	1000000	4504